

# Characterization and grading of the Pixel Vertex Detector modules for Belle II

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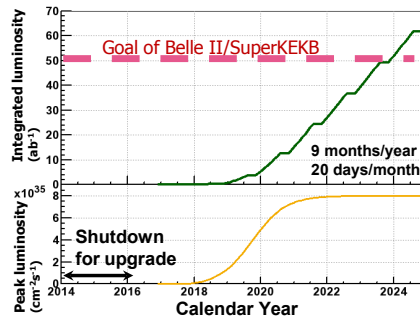
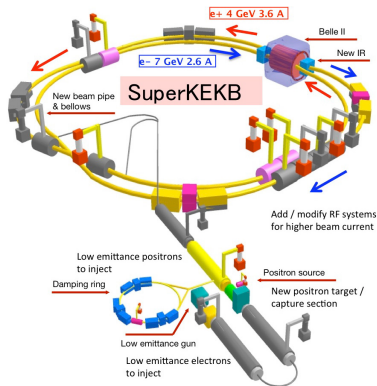
DPG Frühjahrstagung - Münster  
28th of March 2017



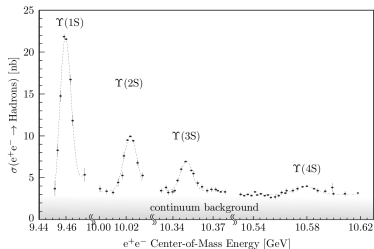
Max-Planck-Institut für Physik  
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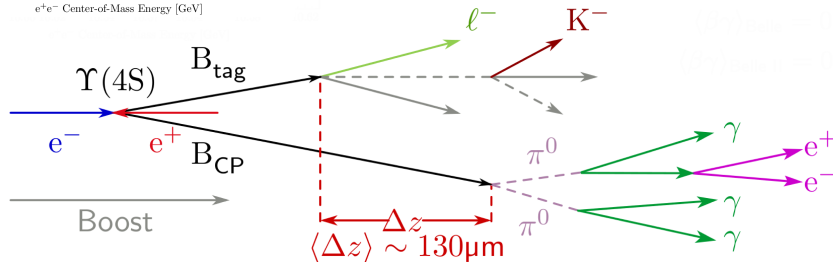
HALBLEITERLABOR  
DER MAX-PLANCK-GESELLSCHAFT



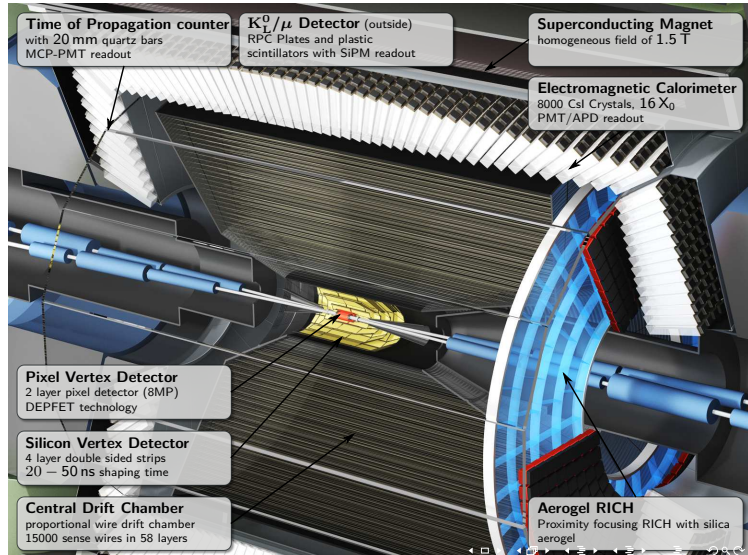
- Upgrade of the KEKB accelerator at the High Energy Accelerator Research Organization in Tsukuba, Japan
- Asymmetrical electron-positron accelerator (7 GeV e<sup>-</sup>, 4 GeV e<sup>+</sup>)
- Design luminosity:  $8 \cdot 10^{35} \text{ cm}^{-2} \text{ s}^{-1}$

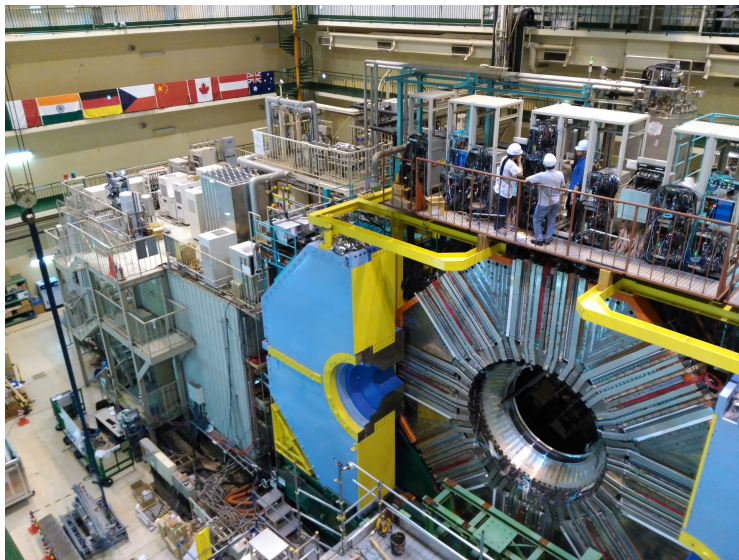


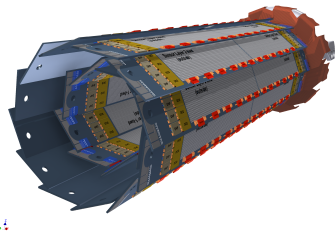
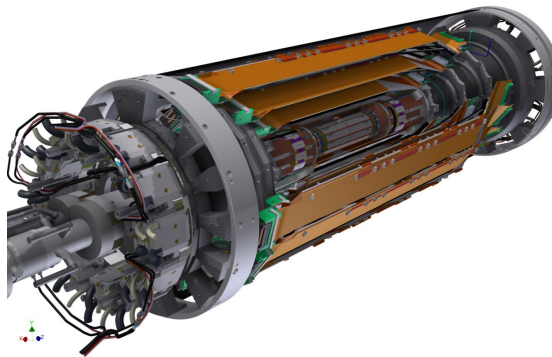
- $\Upsilon(4S)$  resonance at 10.58 GeV
- threshold for  $B\bar{B}$  production



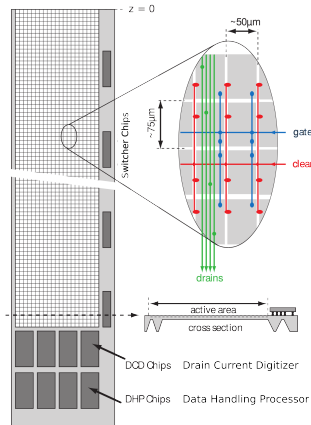
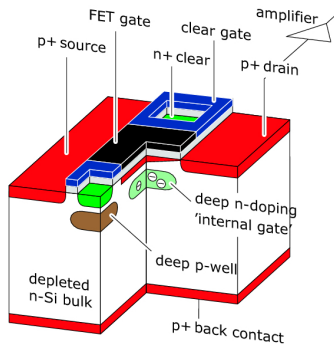
- higher statistics  $\rightarrow$  higher precision and more rare decays
- lower boost as for KEKB  $\rightarrow$  higher vertex resolution necessary
- higher luminosity and higher background  $\rightarrow$  higher occupancy





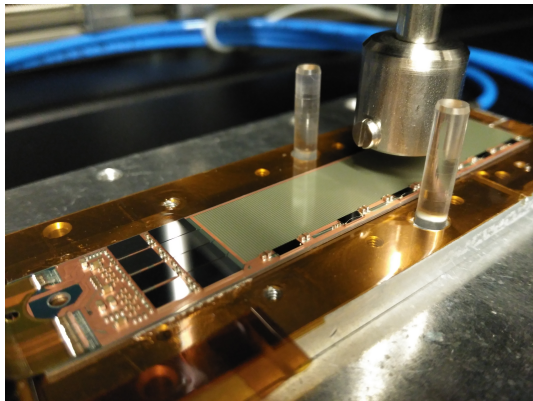


- 2 layers of DEPFET pixel sensors
- 4 layers of silicon strip sensors
- 8 ladders in layer 1 (radius 14 mm)
- 12 ladders in layer 2 (radius 22 mm)
- 40 modules with each 192 000 Pixels
- pixel sizes:  $55 \mu\text{m} \times 50 \mu\text{m}$  up to  $80 \mu\text{m} \times 50 \mu\text{m}$
- frame rate: 50 kHz    row rate: 10 MHz



- DEpleted P-channel Field Effect Transistor
- conversion of charge into current
- internal signal amplification
- just 75 μm thick

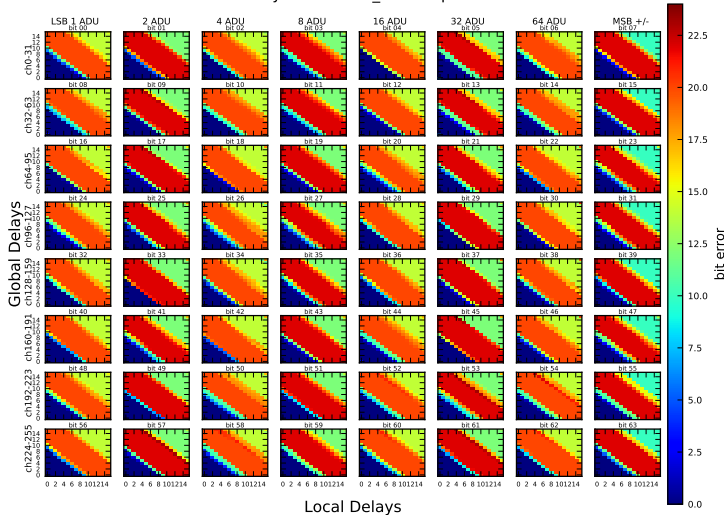
- 3 ASICs for control and readout  
Application-Specific Integrated Circuit
- readout of four lines at the same time
- (active part / total matrix size) = 100 %



- Optimal settings will be detected in various tests and will be stored in a configuration database.  
> 10 000 process variables per module
- Analyzed data/results will be uploaded to a production database. Upon this basis the modules will be evaluated and sorted in to classes.
- The best modules will be used for the PXD.

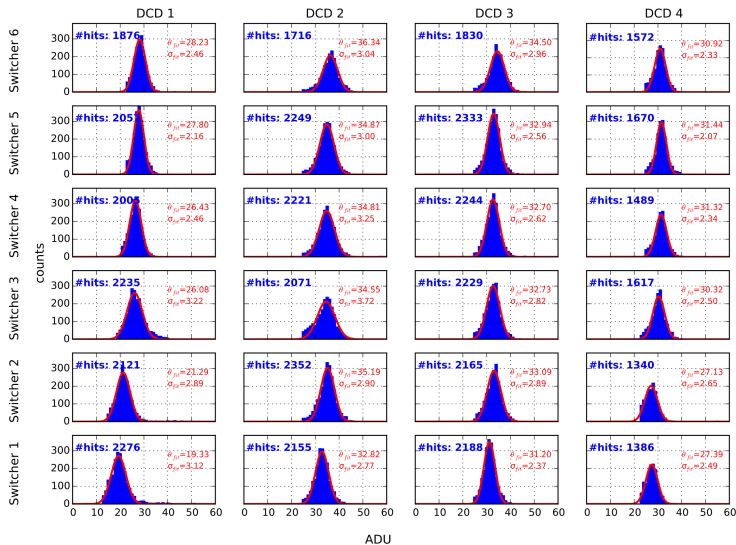


Delay scan - W37\_IB - asicpair: 4



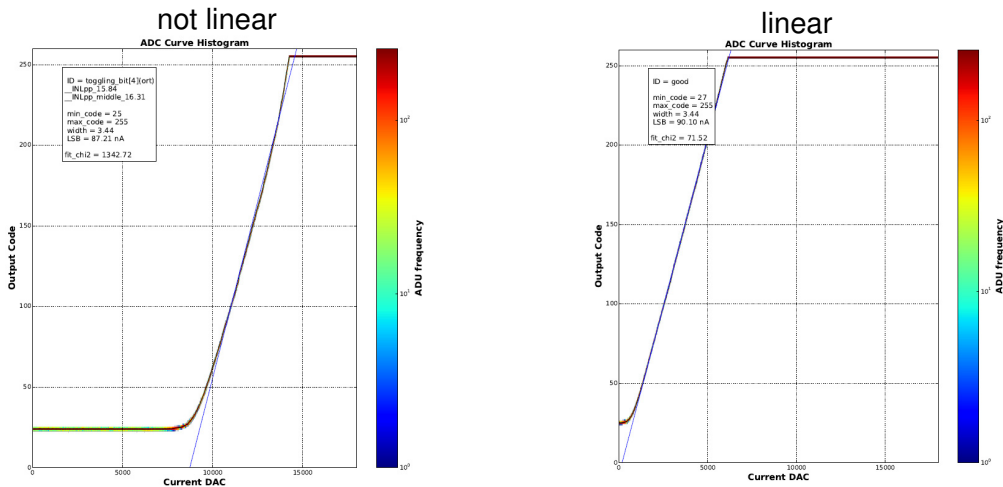
- 2D scan over the delay settings of the communication between Drain Current Digitizer and Data Handling Processor
- Color code indicates the number of faults during transmission of a test pattern.

## Cadmium-109 signal



- reference signal corresponding to a MIP (minimum ionizing particle)
- optimization of the various operation voltages for matrix and ASICs

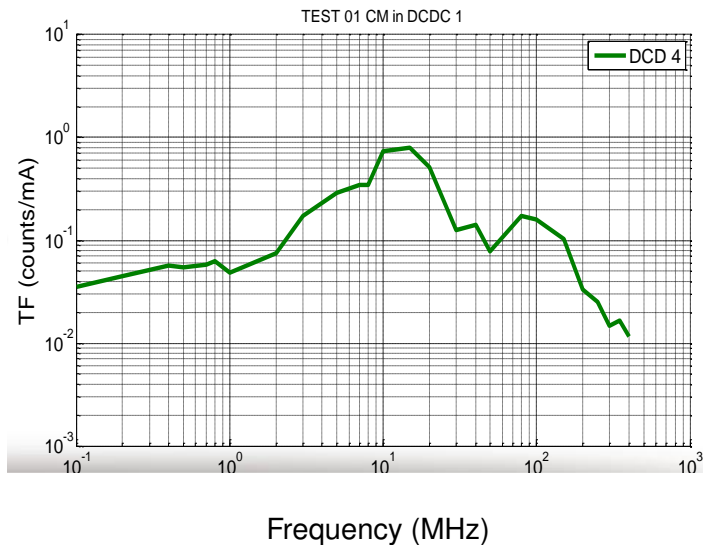
## Linearity of the transfer curves of the analog-to-digital converters



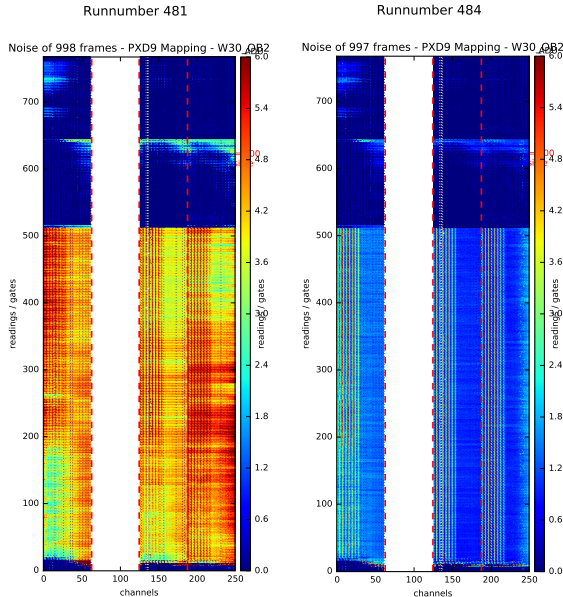
EMC = Electromagnetic Compatibility



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frequency: 20 MHz  
amplitude: 80 dB  
current: 10 mA



frequency: 40 MHz  
amplitude: 84 dB  
current: 16 mA



# Backup



## measurements for each module in detail

- power up and JTAG configuration, voltage checks (digital, analog, matrix)
- JTAG Boundary-Scan
- DHPT link parameter
- DHPT - DCD communication delay-scan
- pedestals (number of working pixels)
- ADC transfer curves
- 2bit offset DACs
- sample point
- DEPFET optimization with Cd-109 source
- clear efficiency with infrared laser
- Gated Mode

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- The best modules will be used for the PXD.